POWERSITETM SURVEY

PowerSite pads allow the soldering of power devices directly to heat sinks with no attachment hardware. They offer excellent thermal performance and electrical isolation.

Please complete the following survey, and return this self-addressed and stamped card to EIS Fabrico. We will forward you a PowerSite prototype assembly and technical literature.

APPLICATION PROFILE		
Application description		Power supply (AC/DC, DC/DC, inverter, UPS), Motion control, Motor control, etc.
Unit size		Watts (power supply), Amps (motion control)
Design location(s) (<i>specification</i>)		Ex., California, Germany, etc.
(specification) Manufacturing location(s)		Ex., New Jersey, Taiwan, etc.
SUBASSEMBLY PROFILE		
Number of devices used annually (est.)		TO-220 TO-247 Power module Other
Waste heat per device (typical / peak)	//	TO-220 TO-247
<i>WASTE HEAT per device = Pow</i> [NOTE: De	waste heat estin wer x (100% - Unit e vice types = FET, di	fficiency) / Number of power devices
How many devices per heat sink? Are devices mounted on one or both sides of the heat sink?		
Attachment method		Screw, clip, bar, etc.
Present interface material		Pad type (please specify)
(Choose one or more)		Other type (please specify) Devices not electrically-isolated
		Case-isolated devices used (ex., Iso-Pak)

Biggest concerns about subassembly Device temperature (in order of priority, l=biggest) Electrical isolation integrity Power device failures now mainly due to Labor cost and consistency How would you use the improvement in thermal performance ? Cooler power device (same part number) Run unit at higher power, with same devices Cheaper power device (different part number) Less devices in assembly (assuming parallel operation) Higher ambient rating of unit Smaller heat sink NEW TECHNOLOGY ADOPTION Existing design New design under development PowerSite technology for? How long does your Qualify new technology (months) Design=>commercialization
(in order of priority, I=biggest) Labor cost and consistency Power device failures now Cooler power device mainly due to Cooler power device How would you use the Run unit at higher power, improvement in thermal Cheaper power device performance ? (different part number) Less devices in assembly Less devices in assembly (in order of priority 1-6. (assuming parallel operation) 1=highest) Higher ambient rating of unit NEW TECHNOLOGY ADOPTION Existing design Would you consider PowerSite technology PowerSite technology Future design How long does your Qualify new technology (months) How long does your Design=>commercialization
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company require to? Introduce new unit
(conceptualization=>market)
POWERSITE SUPPLY CHAIN
Buy turn-key subassemblies, including
Your supply preference: devices and heat sinks
(<i>in order 1-3, 1=highest</i>) Provide devices+heat sinks for toll conversion into subassemblies

Mail the completed survey to EIS Fabrico and receive:

- PowerSite prototype samples (TO-220s soldered to aluminum heat sink)
- PowerSite technical bulletin on thermal performance
- PowerSite technical bulletin on bond durability
- PowerSite product brochure

No purchase necessary.